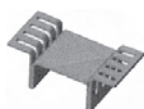


## BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS

Maximum footprint: 1.00" (25.4) x .50" (12.7). Material: aluminum, black anodized.

### VERTICAL MOUNT HEAT SINKS

Cat. No.	Height Above PC Board	Thermal Performance at Typical Load		Net Price
		Natural Convection	Forced Convection	
206-1PABH	1.18" (30.0)	56°C Rise @ 4W	7.3°C/W @ 200LFM	<b>\$.65</b>
265-118ABH-22	1.18" (30.0)	56°C Rise @ 4W	7.3°C/W @ 200LFM	<b>.50</b>



## BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS

Maximum footprint: Model 218-40CT3: .90" (22.9) x 3.15" (8.0). Model 218-40CT5: 1.03" (26.2) x .50" (12.7). Material: aluminum, black anodized.

### SURFACE MOUNT HEAT SINKS

Cat. No.	Height Above PC Board	Thermal Performance at Typical Load		Net Price
		Natural Convection	Forced Convection	
218-40CT3	.40" (10.2)	62°C Rise @ 2W	21°C/W @ 200LFM	<b>\$.52</b>
218-40CT5	.40" (10.2)	62°C Rise @ 2W	21°C/W @ 200LFM	<b>.42</b>

**1-800-56-SONIC**  
**www.e-sonic.com**

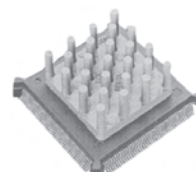


## BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS

Maximum footprint: Model 262-75AB-05: .75" (19.1) x .50" (12.7). Model 262-75AB-01: .53" (13.4) x .50" (12.7). Material: aluminum, black anodized.

### HORIZONTAL AND VERTICAL MOUNT HEAT SINKS

Cat. No.	Height Above PC Board	Thermal Performance at Typical Load		Net Price
		Natural Convection	Forced Convection	
262-75AB-05	.53" (13.4)	80°C Rise @ 3W	10°C/W @ 200LFM	<b>\$.36</b>
262-75AB-01	.75" (19.1)	80°C Rise @ 3W	10°C/W @ 200LFM	<b>.34</b>



## DELTEM™ COMPOSITE HEAT SINKS FOR BGAs

Pin fin heat sink for 169 BGA. Available with pressure sensitive adhesives for quick and easy mounting. Base dimensions (inches (mm) square): .850 (21.6).

Cat. No.	Height In. (mm)	Typical Application	Weight Lbs. (Grams)	Net Price
D10850-40	.400 (10.2)	21 mm BGA	.019 (8.50)	<b>\$.67</b>
D10650-40	.650 (16.5)	21 mm BGA	.013 (5.67)	<b>.66</b>

### HEAT SINK LOCATOR TABLE

JEDEC Case No.	Motorola Case No.	See Case Style No.
TO-3 (TO-204A)	1/11/3/12	TO-3
TO-5 (TO-250AA)	31	TO-5
TO-9	143	TO-5
TO-11		TO-5
TO-12	34A	TO-5
TO-26 TO-29 TO-33 TO-39 TO-43 (TO-205AD)	79	TO-5 TO-5 TO-5 TO-5 TO-5
TO-45 TO-202 TO-218 TO-220	340 221A	TO-5 TO-202/TO-220 TO-218 TO-202/TO-220



260-4T5E



260-4TH5E

### WAKEFIELD TO-5 STYLE HEAT SINKS

Cat. No.	I.D. "A" in. (mm)	O.D. "B" in. (mm)	Height "C" in. (mm)
260-4T5E	.29 (7.4)	.30 (7.6)	.370 (9.5)
260-4TH5E	.29 (7.4)	.30 (7.6)	.400 (10.2)

### WAKEFIELD TO-5 STYLE HEAT SINKS

Cat. No.	Material	Finish	Net Price
260-4T5E	Beryllium Copper	Epoxy Insulated	<b>\$9.01</b>
260-4TH5E	Beryllium Copper	Epoxy Insulated	<b>9.91</b>

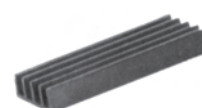
\$Houses 2 devices.  
\*Beryllium Oxide Insulated.



650



651



652

### WAKEFIELD "DIP" STYLE HEAT SINK DIMENSIONS

Cat. No.	Width in. (mm)	Depth in. (mm)	Height in. (mm)
<b>[DELTA 152 OR 155 EPOXY BOND TO 14/16/24/28/40 OR 64 PIN DIPS]</b>			
650-B	.250 (6.35)	.740 (18.80)	.240 (6.10)
651-B	.415 (10.54)	.750 (19.05)	.240 (6.10)
652-5AB	.52 (13.21)	1.25 (31.75)	.19 (4.83)
652-6AB	.52 (13.21)	1.45 (36.83)	.19 (4.83)
652-7AB	.52 (13.21)	2.00 (50.80)	.19 (4.83)
652-8AB	.52 (13.21)	3.20 (81.28)	.19 (4.83)

### WAKEFIELD "DIP" STYLE HEAT SINKS

Cat. No.	Material	Finish	Net Price
<b>(DELTA 152 OR 155 EPOXY BOND TO 14/16/24/28/40 OR 64 PINS DIPS) FOR 14 AND 16 PIN DIPS</b>			
650-B	Aluminum	Black Anodized	<b>\$.89</b>
651-B	Aluminum	Black Anodized	<b>.94</b>
<b>FOR 24/28/40 AND 64 PIN DIPS</b>			
652-5AB	Aluminum	Black Anodized	<b>.99</b>
652-6AB	Aluminum	Black Anodized	<b>1.05</b>
652-7AB	Aluminum	Black Anodized	<b>1.10</b>
652-8AB	Aluminum	Black Anodized	<b>1.16</b>